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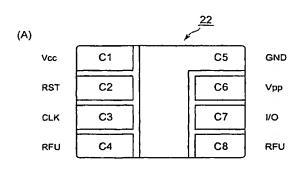
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(71) Applicant (for all designated States except US): DAI NIPPON PRINTING CO., LTD. [IP/IP]; 1-1. Ichigaya-kaga-cho 1-chome, Shinjuku-ku, Tokyo 162-8001 (IP).

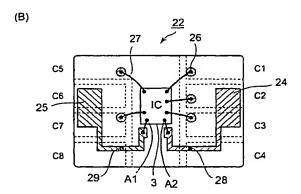
- (72) Inventor; and
- (75) Inventor/Applicant (for US only): NISHIKAWA, Seiichi [JP/JP]; c/o Dai Nippon Printing Co., Ltd., 1-1, Ichigaya-kaga-cho 1-chome. Shinjuku-ku, Tokyo 162-8001 (JP).
- (74) Agents: YOSHITAKE, Kenji et al.; Kyowa Patent & Law Office, Room 323, Fuji Bldg., 2-3, Marunouchi 3-chome, Chiyoda-ku, Tokyo 100-0005 (JP).
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(54) Title: SIM, SIM HOLDER, IC MODULE, IC CARD AND IC CARD HOLDER



(57) Abstract: A SIM comprises a substrate, an IC chip mounted on the substrate and provided with a dual interface for contact and noncontact communication, and a contact-terminal plate mounted on the substrate and provided with a plurality of contact terminals. A SIM holder for holding the SIM is provided with an antenna coil, and the antenna terminals of the IC chip are connected to terminals C4 and C8 among the eight terminals C1 to C8 of the SIM. The terminals C4 and C8 are connected to the antenna coil of the SIM holder.



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